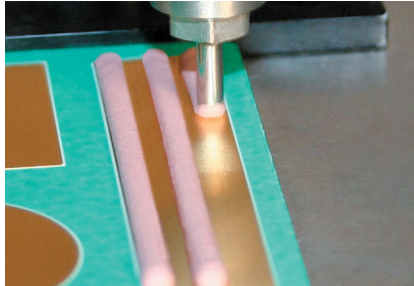


Gap Filler 2000 (Two-Part)

Thermally Conductive, Liquid Gap Filling Material

Features and Benefits

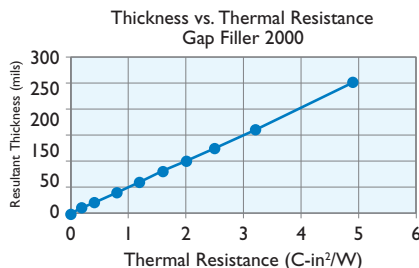
- Thermal conductivity: 2.0 W/m-K
- Ultra-conforming, designed for fragile and low-stress applications
- Ambient and accelerated cure schedules
- 100% solids – no cure by-products
- Excellent low and high temperature mechanical and chemical stability



Gap Filler 2000 is a high performance, thermally conductive, liquid gap filling material supplied as a two-component, room or elevated temperature curing system. The material provides a balance of cured material properties and good compression set (memory). The result is a soft, form-in-place elastomer ideal for coupling “hot” electronic components mounted on PC boards with an adjacent metal case or heat sink. Before cure, it flows under pressure like grease. After cure, it won't pump from the interface as a result of thermal cycling and is dry to the touch.

Unlike cured Gap Filling materials, the liquid approach offers infinite thickness with little or no stress during displacement and assembly. It also eliminates the need for specific pad thickness and die-cut shapes for individual applications.

Gap Filler 2000 is intended for use in thermal interface applications when a strong structural bond is not required. As cured, Gap Filler 2000 is formulated to have pliable low-modulus, properties. *Note: Resultant thickness is defined as the final gap thickness of the application.*



TYPICAL PROPERTIES OF GAP FILLER 2000			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color / Part A	Pink	Pink	Visual
Color / Part B	White	White	—
Viscosity as Mixed (cps) ⁽¹⁾	300,000	300,000	ASTM D2196
Density (g/cc)	2.9	2.9	ASTM D792
Mix Ratio	1:1	1:1	—
Shelf Life @ 25°C (months)	6	6	—
PROPERTY AS CURED			
Color	Pink	Pink	Visual
Hardness (Shore 00) ⁽²⁾	70	70	ASTM D2240
Heat Capacity (J/g-K)	1.0	1.0	ASTM D1269
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL AS CURED			
Dielectric Strength (V/ml)	500	500	ASTM D149
Dielectric Constant (1000 Hz)	7	7	ASTM D150
Volume Resistivity (Ohm-meter)	10 ¹¹	10 ¹¹	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL AS CURED			
Thermal Conductivity (W/m-K)	2.0	2.0	ASTM D5470
CURE SCHEDULE			
Pot Life @ 25°C ⁽³⁾	15 min	60 min	600 min (10 hr)
Cure @ 25°C ⁽⁴⁾	1-2 hours	3-4 hours	3 days
Cure @ 100°C ⁽⁴⁾	5 min	15 min	1 hour

1) Brookfield RV, Heli-Path, Spindle TF @ 20 rpm, 25°C.
 2) Thirty second delay value Shore 00 hardness scale.
 3) Time for viscosity to double.
 4) Cure schedule (rheometer - time to read 90% cure)

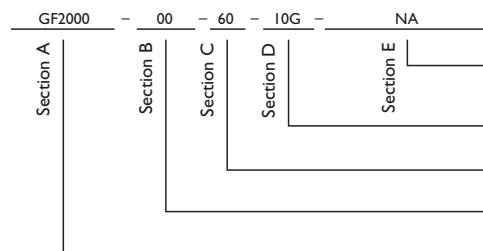
Typical Applications Include:

- Automotive electronics
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink
- Telecommunications
- Thermally conductive vibration dampening

Configurations Available:

- Supplied in cartridge or kit form

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others.

Standard Options

◀ example

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

Cartridges: 50cc = 50.0cc, 400cc = 400.0cc
 Kits: 1200cc = 1200.0cc, or 10G = 10 gallon

Pot Life: 15 = 15 minutes, 60 = 60 minutes
 600 = 600 minutes

00 = No spacer beads
 07 = 0.007" spacer beads

GF2000 = Gap Filler 2000 Material



www.bergquistcompany.com

The Bergquist Company -
 North American Headquarters
 18930 West 78th Street
 Chanhassen, MN 55317
 Phone: 800-347-4572
 Fax: 952-835-0430

The Bergquist Company -
 European Headquarters
 Netherlands
 Phone: 31-35-5380684
 Fax: 31-35-5380295

The Bergquist Company -
 Asia Headquarters
 Hong Kong
 Phone: 852-2690-9296
 Fax: 852-2690-3408

All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND FITNESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using, user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NEITHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER IN TORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL, OR CONSEQUENTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARISING OUT OF THE USE OR THE INABILITY TO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer.